- Members of the Texas Instruments Widebus $+^{\text {TM }}$ Family
- State-of-the-Art EPIC-IIB ${ }^{\text {TM }}$ BiCMOS Design Significantly Reduces Power Dissipation
- UBT ${ }^{\text {TM }}$ (Universal Bus Transceiver) Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, or Clocked Mode
- ESD Protection Exceeds 2000 V per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model ( $\mathrm{C}=\mathbf{2 0 0}$ pF, $\mathrm{R}=0$ )
- Latch-Up Performance Exceeds 500 mA per JEDEC Standard JESD-17
- Typical Volp (Output Ground Bounce) $<0.8 \mathrm{~V}$ at $\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$
- Distributed $V_{C C}$ and GND Pin Configuration Minimizes High-Speed Switching Noise
- High-Drive Outputs (-32-mA IOH, $64-\mathrm{mA} \mathrm{IOL}$ )
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Packaged in 100-Pin Plastic Thin Quad Flat (PZ) Package With $14 \times 14-\mathrm{mm}$ Body Using 0.5-mm Lead Pitch


[^0]
## description

These 36-bit UBTs combine D-type latches and D-type flip-flops to allow data flow in transparent, latched, and clocked modes.

Data flow in each direction is controlled by output-enable (OEAB and $\overline{O E B A}$ ), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the $A$-bus data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. Data flow for $B$ to $A$ is similar to that of $A$ to $B$, but uses $\overline{O E B A}$, LEBA, and CLKBA.

Output-enable OEAB is active high. When OEAB is high, the outputs are active. When OEAB is low, the outputs are in the high-impedance state. The output enables are complementary (OEAB is active high, and OEBA is active low).
To ensure the high-impedance state during power up or power down, $\overline{\mathrm{OEBA}}$ should be tied to $\mathrm{V}_{\mathrm{CC}}$ through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver ( $B$ to $A$ ). OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver (A to B).

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.
The SN54ABT32501 is characterized for operation over the full military temperature range of $-55^{\circ} \mathrm{C}$ to $125^{\circ} \mathrm{C}$. The SN74ABT32501 is characterized for operation from $-40^{\circ} \mathrm{C}$ to $85^{\circ} \mathrm{C}$.

FUNCTION TABLE $\dagger$

| INPUTS |  |  |  | OUTPUT <br> B |
| :---: | :---: | :---: | :---: | :---: |
| OEAB | LEAB | CLKAB | A |  |
| L | X | X | X | Z |
| H | $H$ | $X$ | L | L |
| H | $H$ | $X$ | $H$ | $H$ |
| H | L | $\uparrow$ | L | L |
| H | L | $\uparrow$ | $H$ | $H$ |
| H | L | $H$ | $X$ | $B_{0} \ddagger$ |
| H | L | L | X | $B_{0} \S$ |

$\dagger$ A-to-B data flow is shown: B-to-A flow is similar, but uses $\overline{O E B A}$, LEBA, and CLKBA.
$\ddagger$ Output level before the indicated steady-state input conditions were established
§ Output level before the indicated steady-state input conditions were established, provided that CLKAB was low before LEAB went low

## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted) $\dagger$

| Supply voltage range, $\mathrm{V}_{\mathrm{CC}}$ | -0.5 V to 7 V |
| :---: | :---: |
| Input voltage range, $\mathrm{V}_{\text {I }}$ (except I/O ports) (see Note 1) | -0.5 V to 7 V |
| Voltage range applied to any output in the high state or power-off | -0.5 V to 5.5 V |
| Current into any output in the low state, $\mathrm{I}_{\mathrm{O}}$ : SN54ABT32501 | 96 mA |
| SN74ABT32501 | 128 mA |
| Input clamp current, $\mathrm{I}_{\mathrm{IK}}\left(\mathrm{V}_{\mathrm{I}}<0\right)$ | -18 mA |
| Output clamp current, $\mathrm{I}_{\mathrm{OK}}\left(\mathrm{V}_{\mathrm{O}}<0\right)$ | -50 mA |
| Maximum power dissipation at $\mathrm{T}_{\mathrm{A}}=55^{\circ} \mathrm{C}$ (in still air) (see Note 2) | 1.2 W |
| Operating free-air temperature range, $\mathrm{T}_{\mathrm{A}}$ : SN54ABT32501 | $-55^{\circ} \mathrm{C}$ to $125^{\circ} \mathrm{C}$ |
| SN74ABT32501 | $-40^{\circ} \mathrm{C}$ to $85^{\circ} \mathrm{C}$ |
| Storage temperature range | $-65^{\circ} \mathrm{C}$ to $150^{\circ} \mathrm{C}$ |

$\dagger$ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of $150^{\circ} \mathrm{C}$ and a board trace length of 75 mils. For more information, refer to the Package Thermal Considerations application note in the 1994 ABT Advanced BiCMOS Technology Data Book, literature number SCBD002B.
recommended operating conditions (see Note 3)

|  |  |  | SN54A | T32501 | SN74A | T32501 |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | MIN | MAX | MIN | MAX | UNT |
| $\mathrm{V}_{\mathrm{CC}}$ | Supply voltage |  | 4.5 | 5.5 | 4.5 | 5.5 | V |
| $\mathrm{V}_{\text {IH }}$ | High-level input voltage |  | 2 | 4 | 2 |  | V |
| $\mathrm{V}_{\text {IL }}$ | Low-level input voltage |  |  | 0.8 |  | 0.8 | V |
| $\mathrm{V}_{1}$ | Input voltage |  | 0 | $\mathrm{V}_{C C}$ | 0 | $\mathrm{V}_{\mathrm{CC}}$ | V |
| IOH | High-level output current |  |  | -24 |  | -32 | mA |
| ${ }^{\text {IOL }}$ | Low-level output current |  |  | 48 |  | 64 | mA |
| $\Delta t / \Delta v$ | Input transition rise or fall rate | Outputs enabled | O | 10 |  | 10 | ns/V |
| $\Delta \mathrm{t} / \Delta \mathrm{V}_{\mathrm{CC}}$ | Power-up ramp rate |  | 200 |  | 200 |  | $\mu \mathrm{s} / \mathrm{V}$ |
| $\mathrm{T}_{\mathrm{A}}$ | Operating free-air temperature |  | -55 | 125 | -40 | 85 | ${ }^{\circ} \mathrm{C}$ |

NOTE 3: Unused or floating pins (input or I/O) must be held high or low.

## SN54ABT32501, SN74ABT32501 36-BIT UNIVERSAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS <br> SCBS229B - JUNE 1992 - REVISED NOVEMBER 1994

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

$\dagger$ All typical values are at $\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$.
$\ddagger$ This parameter is specified by characterization.
§ The parameters IOZH and IOZL include the input leakage current.
II For $\mathrm{V}_{\mathrm{CC}}$ between 2.1 V and 4 V , OE should be less than or equal to 0.5 V to ensure a low state.
\# Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
$\|$ This is the increase in supply current for each input that is at the specified TTL voltage level rather than $V_{C C}$ or GND.
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$ (unless otherwise noted) (see Figure 1)

|  | FROM (INPUT) | TO (OUTPUT) | SN54ABT32501 |  |  | SN74ABT32501 |  |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| PARAMETER |  |  | MIN | TYP† | MAX | MIN | TYP $\dagger$ | MAX |  |
| $f_{\text {max }}$ |  |  | 150 |  |  | 150 |  |  | MHz |
| tPLH | A or B | $B$ or A | 1.3 | 2.9 | 4.8 | 1.3 | 2.9 | 4.8 | ns |
| tPHL |  |  | 1.4 | 2.74 | 5.4 | 1.4 | 2.7 | 5.4 |  |
| tPLH | LEAB or LEBA | B or A | 1.6 | 3.4 | 5.3 | 1.6 | 3.4 | 5.3 | ns |
| tPHL |  |  | 1.9 | 3.6 | 5.5 | 1.9 | 3.6 | 5.5 |  |
| tPLH | CLKAB or CLKBA | B or A | 1.5 | 3.2 | 5.3 | 1.5 | 3.2 | 5.3 | ns |
| tPHL |  |  | 1.7 | 3.3 | 5.4 | 1.7 | 3.3 | 5.4 |  |
| tpZH | OEAB or $\overline{O E B A}$ | B or A | 1.2 | 3.2 | 5.6 | 1.2 | 3.2 | 5.6 | ns |
| tPZL |  |  | 1.5 | 3.6 | 6 | 1.5 | 3.6 | 6 |  |
| tPHZ | OEAB or $\overline{O E B A}$ | $B$ or A | 1.8 | 3.6 | 5.9 | 1.8 | 3.6 | 5.9 | ns |
| tPLZ |  |  | 1.7 | 3.5 | 5.6 | 1.7 | 3.5 | 5.6 |  |

$\dagger$ All typical values are at $\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$.

## PARAMETER MEASUREMENT INFORMATION



| TEST | S1 |
| :---: | :---: |
| tPLH/tPHL | Open |
| tPLZ/tPZL | 7 V |
| tPHZ/tPZH | Open |



NOTES: A. $C_{L}$ includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: $\mathrm{PRR} \leq 10 \mathrm{MHz}, \mathrm{Z}_{\mathrm{O}}=50 \Omega, \mathrm{t}_{\mathrm{r}} \leq 2.5 \mathrm{~ns}, \mathrm{t}_{\mathrm{f}} \leq 2.5 \mathrm{~ns}$.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.

Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to Tl's terms and conditions of sale supplied at the time of order acknowledgment.
TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with Tl's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.
TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.
TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from Tl under the patents or other intellectual property of TI .
Reproduction of Tl information in Tl data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated Tl product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify Tl and its representatives against any damages arising out of the use of Tl products in such safety-critical applications.
TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.
TI products are neither designed nor intended for use in automotive applications or environments unless the specific Tl products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.
Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

| Products |  |
| :--- | :--- |
| Amplifiers |  |
| Data Converters | amplifier.ti.com |
| DSP | dataconverter.ti.com |
| Clocks and Timers | dsp.ti.com |
| Interface | www.ti.com/cocks |
| Logic | nterace.ti.com |
| Power Mgmt | ogic.ti.com |
| Microcontrollers | Dowe.ti.com |
| RFID | nicrocontroler.ti.com |
| RF/IF and ZigBee® Solutions | NWw.ti-rfid.com |
|  |  |


| Applications |  |
| :---: | :---: |
| Audio | www.ti.com/audio |
| Automotive | www.ticom/automotive |
| Broadband | www.ti.com/broadband |
| Digital Control | www.ti.com/digitalcontrol |
| Medical | www.ti.com/medica |
| Military | www.ti.com/military |
| Optical Networking | www.ticom/opticalnetwork |
| Security | www.ti.com/security |
| Telephony | www.ti.com/telephony |
| Video \& Imaging | www.ticom/vided |
| Wireless | www.ti.com/wireless |

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2008, Texas Instruments Incorporated


[^0]:    Widebus+, EPIC-IIB, and UBT are trademarks of Texas Instruments Incorporated

